PATENT ABSTRACTS OF JAPAN

(11)Publication number:

07-062528

(43) Date of publication of application: 07.03.1995

(51)Int.CI.

C23C 14/34 B23K 20/00

(21)Application number: 05-209097

(71)Applicant:

TOSHIBA CORP

(22)Date of filing:

24.08.1993

(72)Inventor: **KUDO ISAO**

FUKAZAWA MIHARU

SATO MICHIO KOMATSU TORU

(54) SPUTTERING TARGET

(57) Abstract:

PURPOSE: To prevent abnormal electric discharge between target chips at the time of sputtering and to prevent the generation of particles by combining materials of the same kind and/or materials of different kinds with each other and integrating the target chips by diffusion bonding so that a gap is not left.

CONSTITUTION: A block is formed by alternately combining materials of the same kind and/or materials of different kinds with each other so that a section is allowed to coincide with that of a desired sputtering target. At this time, the diffusion bonding faces of the materials are cleaned, fixed under pressure and diffusion-bonded by heating. The resulting block is cut to a prescribed thickness to obtain the objective mosaic sputtering target.

LEGAL STATUS

[Date of request for examination] 24.08.2000 [Date of sending the examiner's decision of rejection] 22.07.2003

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection] 2003-16137 [Date of requesting appeal against examiner's decision of rejection] 21.08.2003

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office